CLAIMS

What is claimed is:

1. An apparatus comprising:
a plurality of devices formed on a substrate; and
a scribe line area separating each of the plurality of devices; and
a masking material overlying a portion of the scribe line area.

2. The apparatus of claim 1, wherein the masking material is transparent.

3. The apparatus of claim 1, wherein the masking material comprises an acrylate moiety.

4. The apparatus of claim 1, wherein the masking material has a thickness similar to the thickness of a device portion.

5. The apparatus of claim 1, wherein the plurality of devices comprise as one material layer a material comprising one of a colorant.

6. The apparatus of claim 5, wherein the colorant comprises a pigment.

7. The apparatus of claim 1, wherein the plurality of devices each comprise a sensor portion.

8. The apparatus of claim 1, wherein the masking material overlies the entire portion of the scribe line area adjacent the plurality of devices.

9. The apparatus of claim 6, wherein the masking material comprises a plurality of discrete structures occupying less than the entire portion of the scribe line area adjacent the plurality of devices.

10. A semiconductor wafer comprising:
a plurality of devices formed on the wafer, each integrated circuit

mapped on the surface of a wafer adjacent a scribe line area; and

a masking material overlying a portion of the scribe line area.

11. The semiconductor wafer of claim 10, wherein the masking material is transparent.

12. The semiconductor wafer of claim 10, wherein the masking material has a thickness similar to the thickness of a device portion.

13. The semiconductor wafer of claim 4, wherein the plurality of integrated circuits comprise as one material layer, a material comprising one of a colorant.

14. The semiconductor wafer of claim 13, wherein the colorant comprises a pigment.

15. The semiconductor wafer of claim 10, wherein the plurality of devices comprise a sensor portion.

16. The semiconductor wafer of claim 10, wherein the masking material overlies the entire portion of the scribe line area adjacent the plurality of devices.

17. The semiconductor wafer of claim 10, wherein the masking material comprises a plurality of discrete structures occupying less than the entire portion of the scribe line area adjacent the plurality of devices.